

GENERAL INFORMATION:

When mounted on the appropriate heat sink, these chips will provide high power dissipation.

GENERAL SPECIFICATIONS:

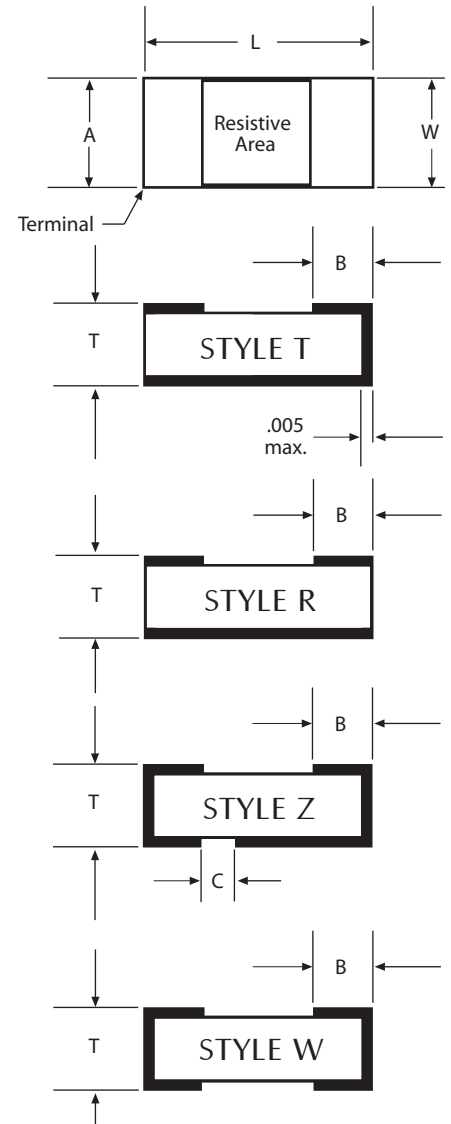
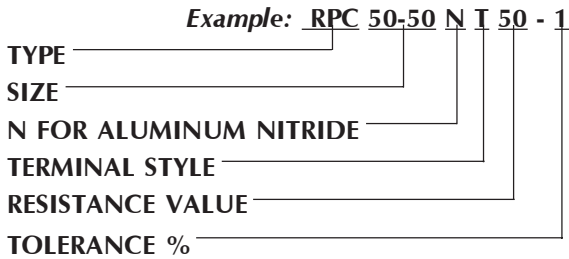
DC Voltage (Maximum): $E = \sqrt{(A \times B)}$
 Resistive Tolerance: 1%, 2%, 5%, 10%
 Terminals: Tin over Nickel
 Substrate: Beryllium Oxide Ceramic or Aluminum Nitride
 Resistive: Element: Proprietary Film
 Environment: Meets applicable portions of MIL-PRF-55342

NOTES:

1. The "L" and "T" dimensions are for the substrate only and do not include terminal thickness or optional tinning thickness.
2. Thermal Resistance ($R\theta^\circ$) is measured in $^\circ\text{C}/\text{W}$ between resistive film and mounting surface.
3. The CW power rating is based on maximum film temperature of $+150^\circ\text{C}$ and with maximum heatsink temperature of $+100^\circ\text{C}$. Power is based on infinite and ideal heatsink. Type "W" and "Z" termination style does not have full back plane metallization and typically handles less power.

HOW TO ORDER BY PART NUMBER:

The part number is a combination of type, size, terminal style, resistance value and tolerance.



RPC TYPE	W ±.005	L ±.005 (NOTE 1)	T ±.005 (NOTE 1)	A ±.008	B ±.010	C ±.005	$R\theta^\circ\text{C}/\text{W}$ (max.) (NOTE 2)		CW POWER (max.) (NOTE 2)	
							Beo	ALN	Beo	ALN
100-200-4	.100	.200	.040	.100	.040	.040	.80	.55	67	46
230-350-4	.350	.230	.040	.187	.040	.040	.35	.24	150	104
250-250-4	.250	.250	.040	.187	.060	.040	.30	.21	169	117
250-250-6	.250	.250	.060	.187	.060	.040	.45	.31	112	78
250-375-4	.250	.375	.040	.220	.060	.060	.15	.11	250	225
250-375-1	.250	.375	.135	.220	.060	.060	.50	.35	108	75
375-375-4	.375	.375	.040	.250	.060	.060	.11	.08	306	212
500-500-4	.500	.500	.040	.375	.060	-	.07	.05	510	353
1000-1000-6	1.000	1.000	.060	.412	.090	-	.05	.03	700	485